

TC74AC367P, TC74AC367F, TC74AC367FN, TC74AC367FT

Hex Bus Buffer (3-state)

The TC74AC367 is an advanced high speed CMOS HEX BUS BUFFERS fabricated with silicon gate and double-layer metal wiring C²MOS technology.

It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

It contains six buffers; four buffers are controlled by an enable input ($\overline{G1}$), and the other two buffers are controlled by another enable input ($\overline{G2}$). The outputs of each buffer group are enabled when $\overline{G1}$ and/or $\overline{G2}$ inputs are held low; if held high, these outputs are in a high impedance state.

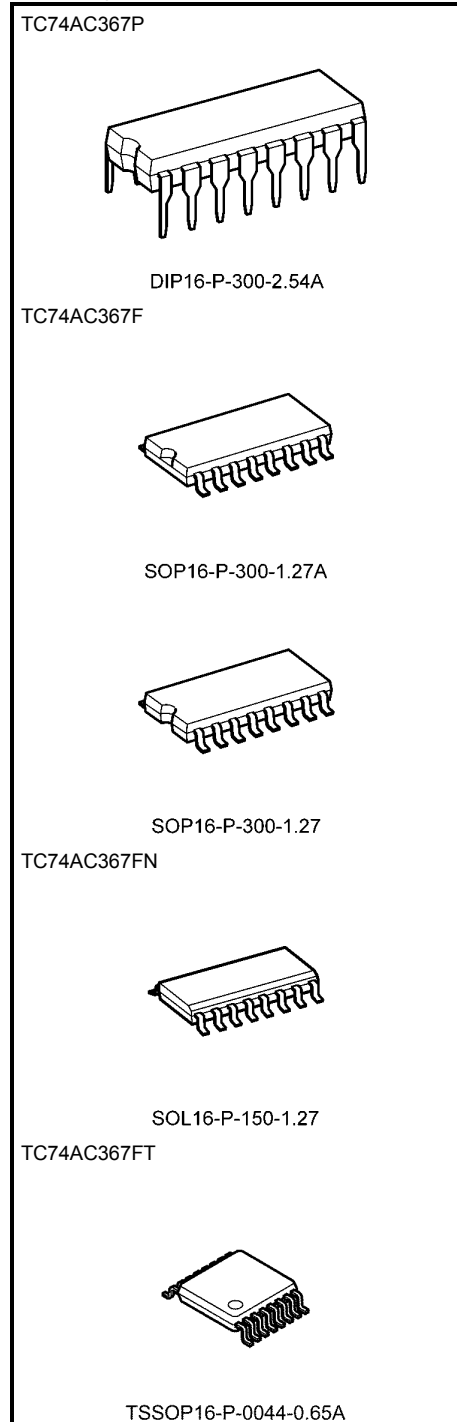
All inputs are equipped with protection circuits against static discharge or transient excess voltage.

Features

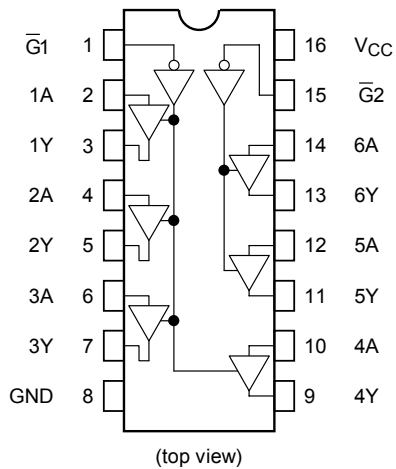
- High speed: $t_{pd} = 3.7$ ns (typ.) at $V_{CC} = 5$ V
- Low power dissipation: $I_{CC} = 8$ μ A (max) at $T_a = 25^\circ$ C
- High noise immunity: $V_{NIH} = V_{NIL} = 28\%$ V_{CC} (min)
- Symmetrical output impedance: $|I_{OH}| = I_{OL} = 24$ mA (min)
Capability of driving 50 Ω transmission lines.
- Balanced propagation delays: $t_{pLH} \approx t_{pHL}$
- Wide operating voltage range: $V_{CC} (opr) = 2$ to 5.5 V
- Pin and function compatible with 74F367

Weight	
DIP16-P-300-2.54A	: 1.00 g (typ.)
SOP16-P-300-1.27A	: 0.18 g (typ.)
SOP16-P-300-1.27	: 0.18 g (typ.)
SOL16-P-150-1.27	: 0.13 g (typ.)
TSSOP16-P-0044-0.65A	: 0.06 g (typ.)

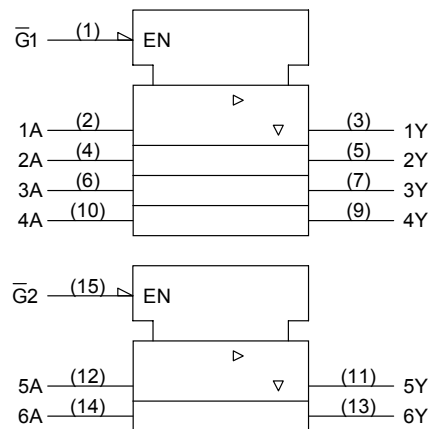
Note: xxxFN (JEDEC SOP) is not available in Japan.



Pin Assignment



IEC Logic Symbol



Truth Table

Inputs		Output
\bar{G}	A	Y
L	L	L
L	H	H
H	X	Z

X: Don't care

Z: High impedance

Absolute Maximum Ratings (Note 1)

Characteristics	Symbol	Rating	Unit
Supply voltage range	V_{CC}	-0.5 to 7.0	V
DC input voltage	V_{IN}	-0.5 to $V_{CC} + 0.5$	V
DC output voltage	V_{OUT}	-0.5 to $V_{CC} + 0.5$	V
Input diode current	I_{IK}	± 20	mA
Output diode current	I_{OK}	± 50	mA
DC output current	I_{OUT}	± 50	mA
DC V_{CC} /ground current	I_{CC}	± 150	mA
Power dissipation	P_D	500 (DIP) (Note 2)/180 (SOP/TSSOP)	mW
Storage temperature	T_{stg}	-65 to 150	$^{\circ}C$

Note1: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Note2: 500 mW in the range of $T_a = -40$ to $65^{\circ}C$. From $T_a = 65$ to $85^{\circ}C$ a derating factor of -10 mW/ $^{\circ}C$ should be applied up to 300 mW.

Recommended Operating Conditions (Note)

Characteristics	Symbol	Rating	Unit
Supply voltage	V_{CC}	2.0 to 5.5	V
Input voltage	V_{IN}	0 to V_{CC}	V
Output voltage	V_{OUT}	0 to V_{CC}	V
Operating temperature	T_{opr}	-40 to 85	°C
Input rise and fall time	dt/dV	0 to 100 ($V_{CC} = 3.3 \pm 0.3$ V) 0 to 20 ($V_{CC} = 5 \pm 0.5$ V)	ns/V

Note: The recommended operating conditions are required to ensure the normal operation of the device.
Unused inputs must be tied to either V_{CC} or GND.

Electrical Characteristics

DC Characteristics

Characteristics	Symbol	Test Condition	$T_a = 25^\circ\text{C}$			$T_a = -40$ to 85°C		Unit		
			V_{CC} (V)	Min	Typ.	Max	Min		Max	
High-level input voltage	V_{IH}	—	2.0	1.50	—	—	1.50	—	V	
			3.0	2.10	—	—	2.10	—		
			5.5	3.85	—	—	3.85	—		
Low-level input voltage	V_{IL}	—	2.0	—	—	0.50	—	0.50	V	
			3.0	—	—	0.90	—	0.90		
			5.5	—	—	1.65	—	1.65		
High-level output voltage	V_{OH}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -50 \mu\text{A}$	2.0	1.9	2.0	—	1.9	—	V
				3.0	2.9	3.0	—	2.9	—	
				4.5	4.4	4.5	—	4.4	—	
				5.5	—	—	—	—	—	
Low-level output voltage	V_{OL}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OL} = 50 \mu\text{A}$	2.0	—	0.0	0.1	—	0.1	V
				3.0	—	0.0	0.1	—	0.1	
				4.5	—	0.0	0.1	—	0.1	
				5.5	—	—	—	—	—	
Low-level output voltage	V_{OL}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OL} = 12 \text{ mA}$	3.0	—	—	0.36	—	0.44	V
				4.5	—	—	0.36	—	0.44	
				5.5	—	—	—	—	1.65	
				5.5	—	—	—	—	—	
3-state output off-state current	I_{OZ}	$V_{IN} = V_{IH}$ or V_{IL} $V_{OUT} = V_{CC}$ or GND	5.5	—	—	± 0.5	—	± 5.0	μA	
Input leakage current	I_{IN}	$V_{IN} = V_{CC}$ or GND	5.5	—	—	± 0.1	—	± 1.0	μA	
Quiescent supply current	I_{CC}	$V_{IN} = V_{CC}$ or GND	5.5	—	—	8.0	—	80.0	μA	

Note: This spec indicates the capability of driving 50 Ω transmission lines.

One output should be tested at a time for a 10 ms maximum duration.

AC Characteristics ($C_L = 50 \text{ pF}$, $R_L = 500 \text{ }\Omega$, input: $t_r = t_f = 3 \text{ ns}$)

Characteristics	Symbol	Test Condition	Ta = 25°C			Ta = -40 to 85°C		Unit	
			V _{CC} (V)	Min	Typ.	Max	Min		Max
Propagation delay time	t _{pLH}	—	3.3 ± 0.3	—	6.5	11.0	1.0	12.5	ns
	t _{pHL}		5.0 ± 0.5	—	4.5	7.0	1.0	8.0	
Output enable time	t _{pZL}	—	3.3 ± 0.3	—	7.9	13.2	1.0	15.0	ns
	t _{pZH}		5.0 ± 0.5	—	5.5	8.7	1.0	10.0	
Output disable time	t _{pLZ}	—	3.3 ± 0.3	—	6.3	10.5	1.0	12.0	ns
	t _{pHZ}		5.0 ± 0.5	—	5.2	7.9	1.0	9.0	
Input capacitance	C _{IN}	—	—	5	10	—	10	pF	
Output capacitance	C _{OUT}	—	—	10	—	—	—	pF	
Power dissipation capacitance	C _{PD}	(Note)	—	28	—	—	—	pF	

Note: C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

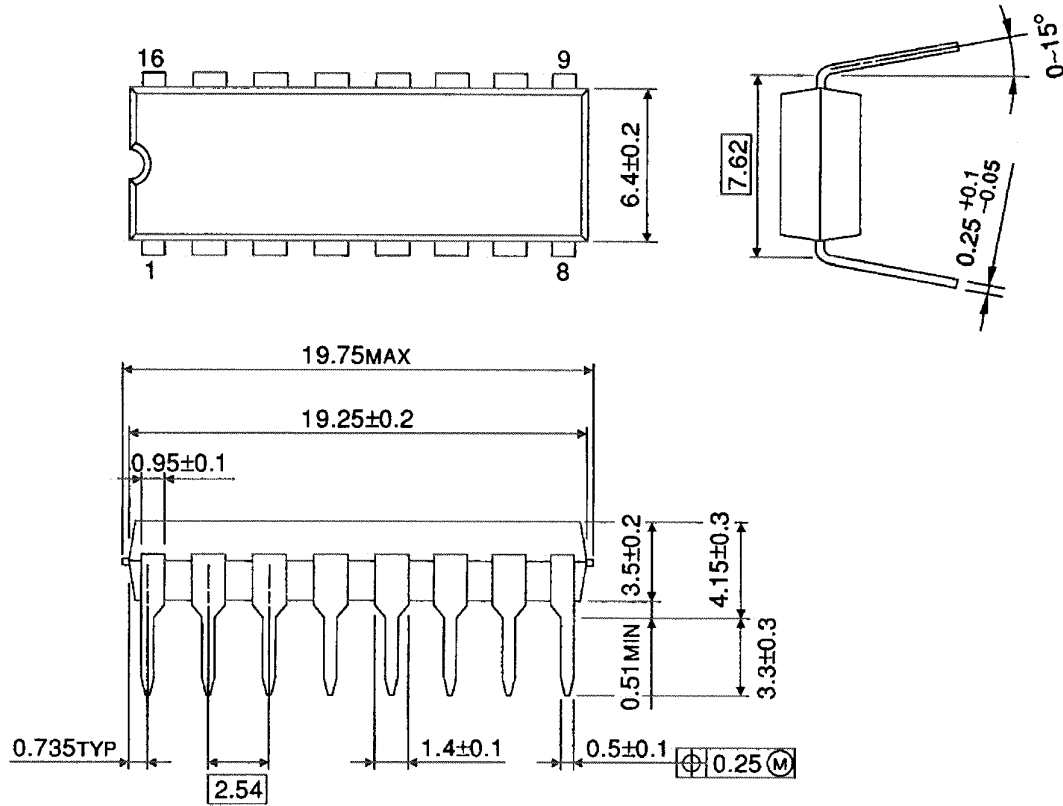
Average operating current can be obtained by the equation:

$$I_{CC (opr)} = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}/6 \text{ (per bit)}$$

Package Dimensions

DIP16-P-300-2.54A

Unit : mm

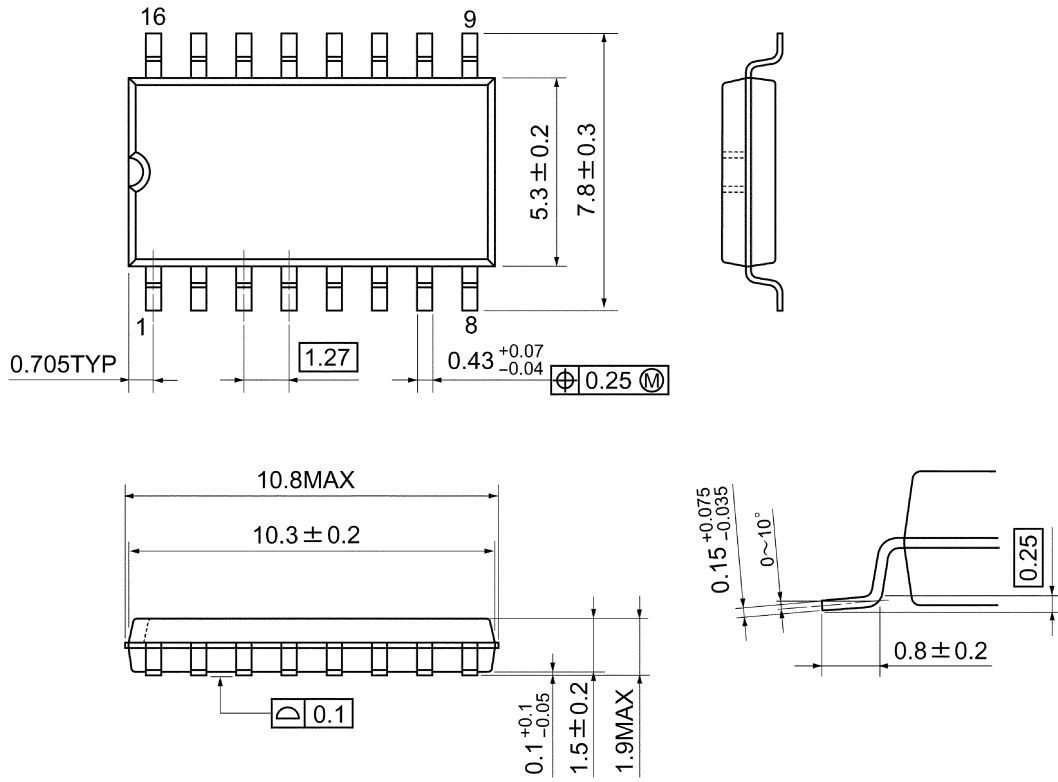


Weight: 1.00 g (typ.)

Package Dimensions

SOP16-P-300-1.27A

Unit: mm

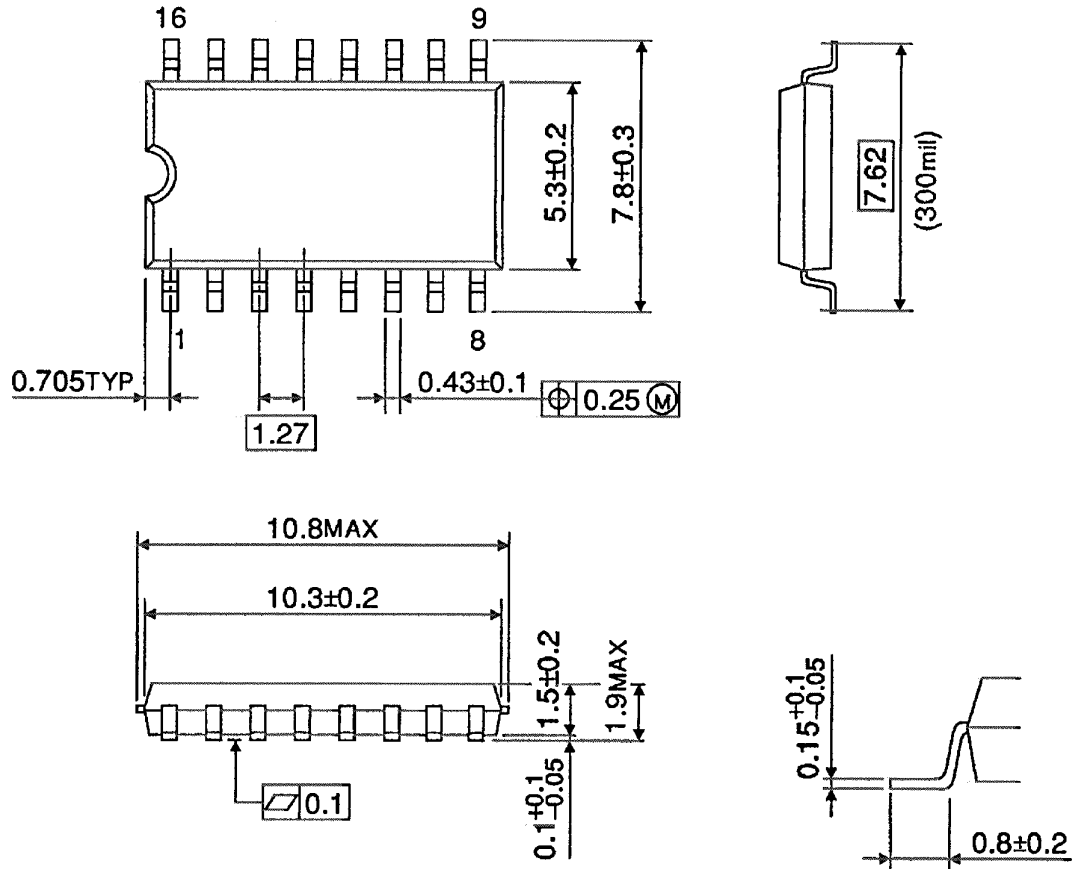


Weight: 0.18 g (typ.)

Package Dimensions

SOP16-P-300-1.27

Unit : mm

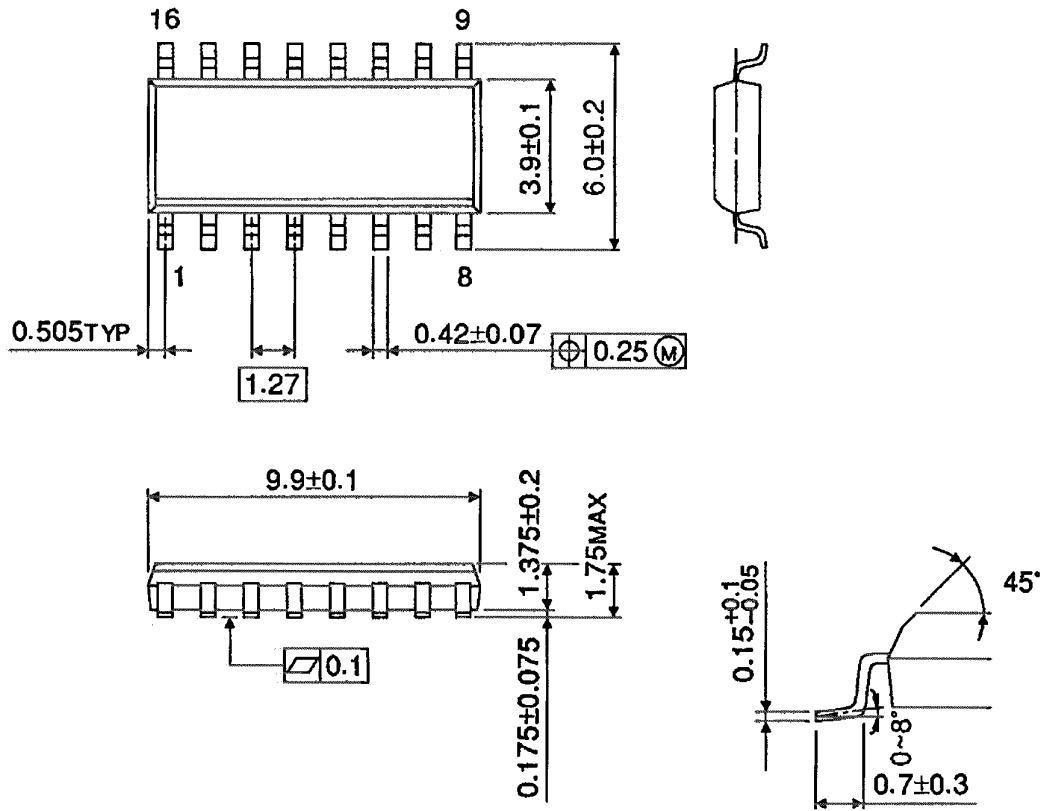


Weight: 0.18 g (typ.)

Package Dimensions (Note)

SOL16-P-150-1.27

Unit : mm



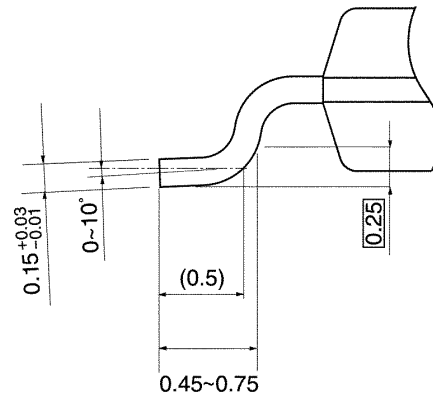
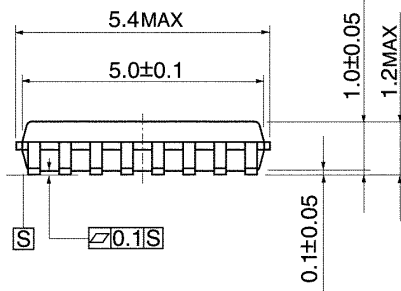
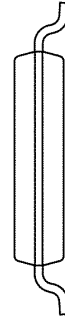
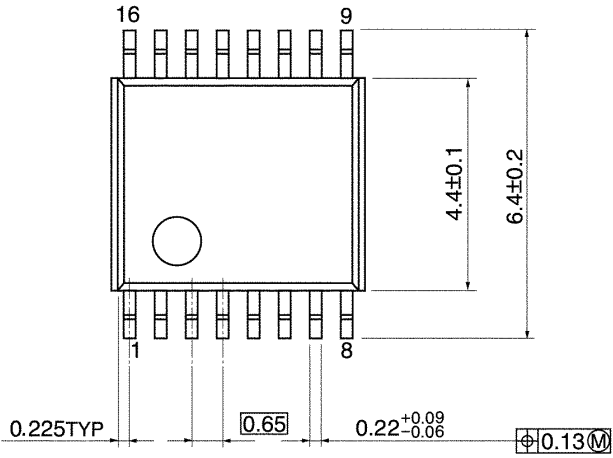
Note: This package is not available in Japan.

Weight: 0.13 g (typ.)

Package Dimensions

TSSOP16-P-0044-0.65A

Unit: mm



Weight: 0.06 g (typ.)

Note: Lead (Pb)-Free Packages**DIP16-P-300-2.54A SOP16-P-300-1.27A SOL16-P-150-1.27 TSSOP16-P-0044-0.65A****RESTRICTIONS ON PRODUCT USE**

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